

MODEL: HSB18-232310 | **DESCRIPTION:** HEAT SINK**FEATURES**

- BGA design
- top mount
- aluminum alloy
- black anodized finish

**MODEL**

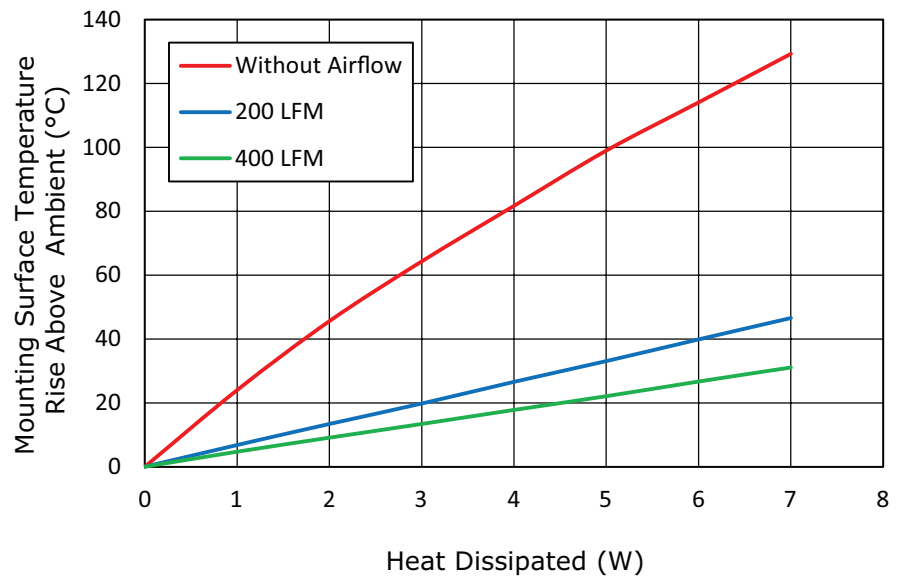
	thermal resistance ¹				power dissipation ¹
	@ 75°C ΔT, nat conv [°C/W]	@ 1 W, nat conv [°C/W]	@ 1 W, 200 LFM [°C/W]	@ 1 W, 400 LFM [°C/W]	@ 75°C ΔT, nat conv [W]
HSB18-232310	20.41	24.0	6.8	4.7	3.67

Note: 1. See performance curves for full thermal resistance details.

PERFORMANCE CURVES

Power [W]	Heatsink Temperature Rise Above Ambient (ΔT = T _{hs} - T _a) [°C]		
	Natural Conv.	200 LFM	400 LFM
0	0	0	0
1	24.0	6.8	4.7
2	45.6	13.4	9.1
3	64.3	19.8	13.4
4	81.7	26.6	17.8
5	99.0	33.1	22.1
6	114.1	39.9	26.7
7	129.3	46.6	31.1

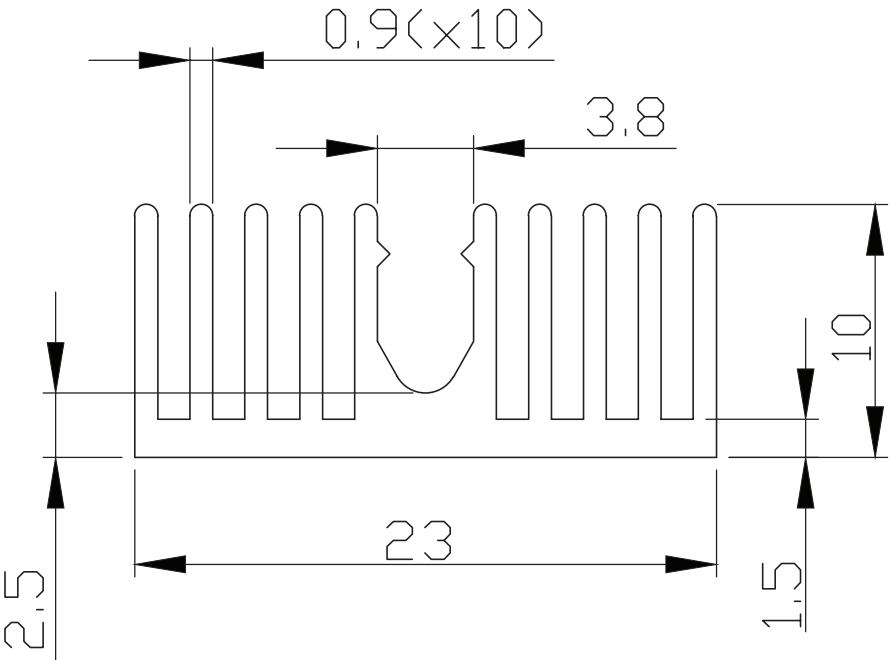
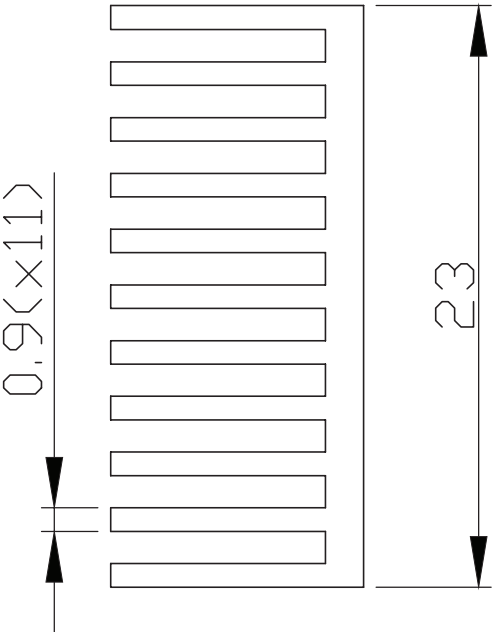
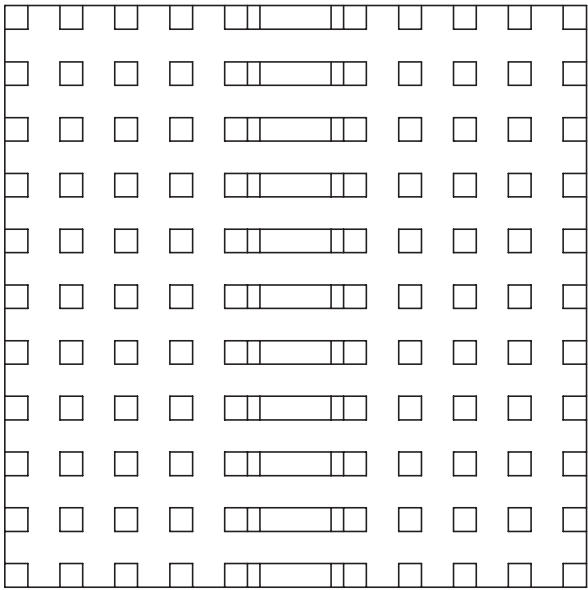
T_{hs}: "hot spot" temperature measured on the heatsink
T_a: ambient temperature



MECHANICAL DRAWING

units: mm
tolerance: ±0.38 mm

MATERIAL	AL 6063-T5
FINISH	black anodized
WEIGHT	4.8 g



REVISION HISTORY

rev.	description	date
1.0	initial release	06/24/2021
1.01	logo, datasheet style update	08/05/2022

The revision history provided is for informational purposes only and is believed to be accurate.



CUI Devices offers a one (1) year limited warranty. Complete warranty information is listed on our website.

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